

N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

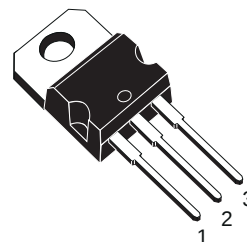
PRELIMINARY DATA

TYPE	V _{DSS}	R _{DS(on)}	I _D
STP53N08	80 V	< 0.024 Ω	53 A

- TYPICAL R_{DS(on)} = 0.018 Ω
- AVALANCE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- 175 °C OPERATING TEMPERATURE
- APPLICATION ORIENTED CHARACTERIZATION

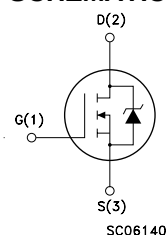
APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- REGULATORS
- DC-DC & DC-AC CONVERTERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMPDRIVERS, Etc.)



TO-220

INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	80	V
V _{DGR}	Drain- gate Voltage (R _{GS} = 20 kΩ)	80	V
V _{GS}	Gate-source Voltage	± 20	V
I _D	Drain Current (continuous) at T _c = 25 °C	53	A
I _D	Drain Current (continuous) at T _c = 100 °C	37	A
I _{DM} (•)	Drain Current (pulsed)	212	A
P _{tot}	Total Dissipation at T _c = 25 °C	150	W
	Derating Factor	1	W/°C
T _{stg}	Storage Temperature	-65 to 175	°C
T _j	Max. Operating Junction Temperature	175	°C

(•) Pulse width limited by safe operating area

THERMAL DATA

$R_{thj-case}$	Thermal Resistance Junction-case	Max	1	$^{\circ}C/W$
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max	62.5	$^{\circ}C/W$
$R_{thj-amb}$	Thermal Resistance Case-sink	Typ	0.5	$^{\circ}C/W$
T_l	Maximum Lead Temperature For Soldering Purpose		300	$^{\circ}C$

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max, $\delta < 1\%$)	53	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_j = 25^{\circ}C$, $I_D = I_{AR}$, $V_{DD} = 25 V$)	600	mJ
E_{AR}	Repetitive Avalanche Energy (pulse width limited by T_j max, $\delta < 1\%$)	150	mJ
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive ($T_c = 100^{\circ}C$, pulse width limited by T_j max, $\delta < 1\%$)	37	A

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}C$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250 \mu A$ $V_{GS} = 0$	80			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating} \times 0.8$ $T_c = 125^{\circ}C$			250 1000	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20 V$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu A$	2	3	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10 V$ $I_D = 26.5 A$ $V_{GS} = 10 V$ $I_D = 26.5 A$ $T_c = 100^{\circ}C$		0.018	0.024 0.048	Ω Ω
$I_{D(on)}$	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 V$	53			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs} (*)$	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 26.5 A$	20	38		S
C_{iss}	Input Capacitance	$V_{DS} = 25 V$ $f = 1 MHz$ $V_{GS} = 0$		4200	5500	pF
C_{oss}	Output Capacitance			700	900	pF
C_{rss}	Reverse Transfer Capacitance			160	210	pF

ELECTRICAL CHARACTERISTICS (continued)**SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Time Rise Time	$V_{DD} = 40\text{ V}$ $R_G = 4.7\ \Omega$	$I_D = 26.5\text{ A}$ $V_{GS} = 10\text{ V}$	30 90	45 130	ns ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 64\text{ V}$ $R_G = 47\ \Omega$	$I_D = 53\text{ A}$ $V_{GS} = 10\text{ V}$	380		A/ μ s
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 10\text{ V}$ $I_D = 53\text{ A}$ $V_{GS} = 64\text{ V}$		120 20 45	170	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$ t_f t_c	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 64\text{ V}$ $R_G = 4.7\ \Omega$	$I_D = 53\text{ A}$ $V_{GS} = 10\text{ V}$	35 45 80	50 65 115	ns ns ns

SOURCE DRAIN DIODE

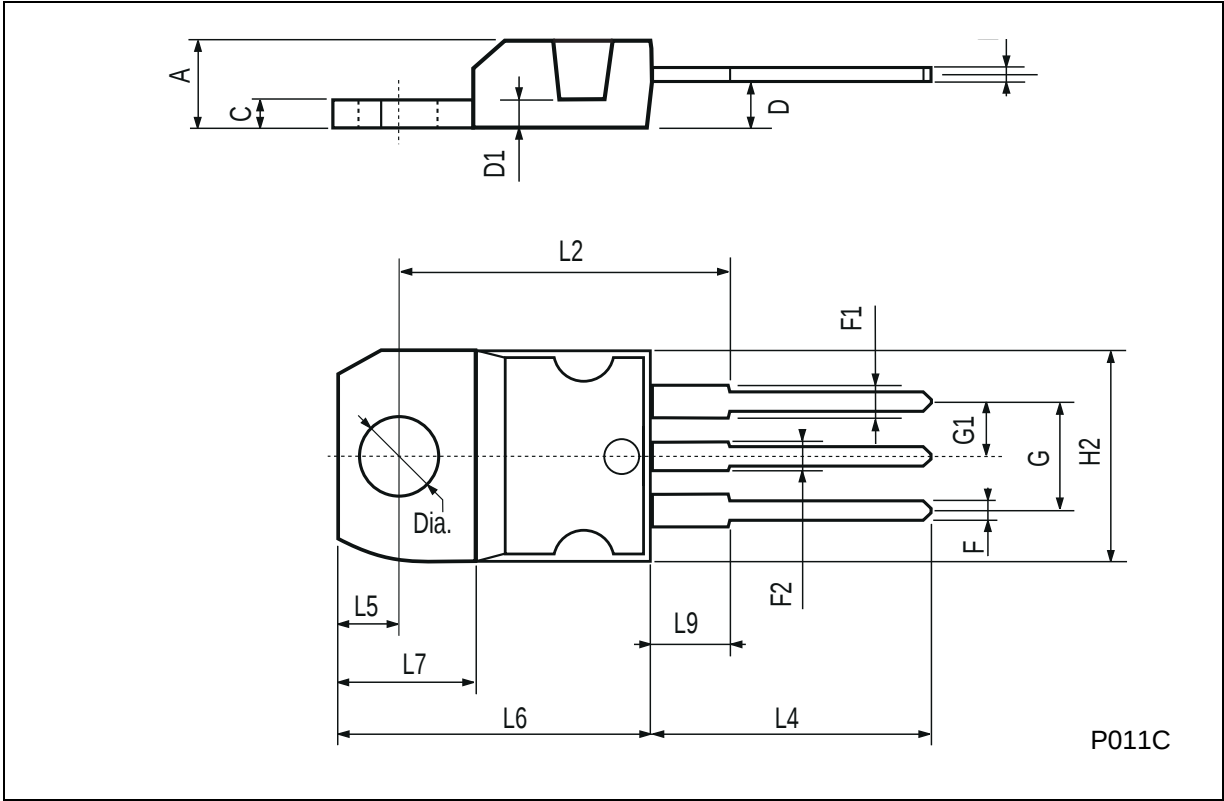
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				53 212	A A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 60\text{ A}$ $V_{GS} = 0$			1.5	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 53\text{ A}$ $V_{DD} = 25\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$ $T_J = 150\text{ }^\circ\text{C}$		180 1 11		ns μ C A

(*) Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area

TO-220 MECHANICAL DATA

DIM.	mm			inch																
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.														
A	4.40		4.60	0.173		0.181														
C	1.23		1.32	0.048		0.051														
D	2.40		2.72	0.094		0.107														
D1		1.27			0.050															
E	0.49		0.70	0.019		0.027														
F	0.61		0.88	0.024		0.034														
F1	1.14		1.70	0.044		0.067														
F2	1.14		1.70	0.044		0.067														
G	4.95		5.15	0.194		0.203														
G1	2.4		2.7	0.094		0.106														
H2	10.0		10.40	0.393		0.409														
L2		16.4			0.645															
L4	13.0		14.0	0.511		0.551														
L5	2.65		2.95	0.104		0.116														
L6	15.25		15.75	0.600		0.620														
L7	6.2		6.6	0.244		0.260 </tr <tr><td>L9</td><td>3.5</td><td></td><td>3.93</td><td>0.137</td><td></td><td>0.154</td></tr> <tr><td>DIA.</td><td>3.75</td><td></td><td>3.85</td><td>0.147</td><td></td><td>0.151</td></tr>	L9	3.5		3.93	0.137		0.154	DIA.	3.75		3.85	0.147		0.151
L9	3.5		3.93	0.137		0.154														
DIA.	3.75		3.85	0.147		0.151														



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